

INT-03-001



June 23, 2004

Commissioner for Patents  
P.O.Box 1450  
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572  
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Subject: | Serial No. 10/780,214 02/17/04 |

Thomas Aisenbrey

LOW COST ANTENNAS AND ELECTRO-  
MAGNETIC (EMP) ABSORPTION IN  
ELECTRONIC CIRCUIT PACKAGES OR  
TRANSCIVERS USING CONDUCTIVE  
LOADED RESIN-BASED MATERIALS

#### SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
mail in an envelope addressed to: Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450, on June 29, 2004.

George O. Saile, Reg.# 19572

Signature/Date

*George O. Saile 6/29/04*

European Patent Application EP 1 233 426 A to Aisenbrey, "Antennas with Conductive Plastics or Conductive Composites," discusses antennas formed of conductive loaded resin-based materials comprising micron conductive powders or micron conductive fibers.

European Patent Application 0 117 700 A to Kuraray Co., Ltd., "Rigid Resin Composition Having Electromagnetic Shielding Properties," discloses hybrid resins having electromagnetic shielding properties.

Translations of the abstracts of the following four Japanese Patents are attached:

Patent Abstracts of Japan 02250203 to Ishikawa Minoru, "Copper Alloy Fiber and Copper Alloy Fiber Bundle to be Added to Conductive Plastic," discusses improving electromagnetic wave shielding characteristics of an injection-molded product and the prevention of deterioration of the characteristics at the time of long-term use by simultaneously adding to Cu Zn and one or two or more of Al, Mg, Sn and Cr.

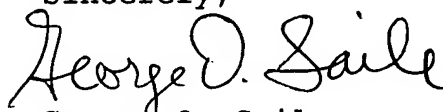
Patent Abstracts of Japan 07162220 to Maeda Takeyasu, "Antenna Module," discusses an antenna module molded out of insulating resin and conductive resin into which the insulating resin molding is inserted.

Patent Abstracts of Japan 2000169641 to Gotou Hidekatsu, "Rubber Composition," discusses obtaining a rubber composition, suppressing the elevation of its viscosity, even blending a large amount of carbon black, and capable of producing an electromagnetic wave shielding material and an electric conductive rubber part in a good processing property.

Patent Abstracts of Japan 06231869 to Sasaki Tsuneji, "Composite Rubber Heating Body Product and Manufacture Thereof," discusses high bending and compressive strength or the like, and improving a heating zone by using a vulcanized rubber sheet evenly containing the metal powder of the specified grain size and the carbon fiber or the specified content ratio.

UK Patent Application GB 2 377 449 A to Sayers, "Electrically Conductive Polymer Composition," discloses electrically conductive compositions and thier use to prevent electrostatic discharges and to earth electrical devices.

Sincerely,

A handwritten signature in cursive script that reads "George O. Saile". The signature is written in dark ink and is positioned above the printed name and registration number.

George O. Saile,  
Reg. No. 19572



Form PTO-1449

## INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

DocId: 34567890 (Optional)

INT-03-001

Application Number

10 | 780, 214

Applicant:

Applicant: Thomas Aisenbrey

Filing Date

Filing Date 02/17/04

Group Art Unit

## U. S. PATENT DOCUMENTS

[illegible]

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO
JP 0	6231869	8/19/94	Japan	H05B	3/14		
GB 2	377449A	7/23/01	United Kingdom	C08K	3/08		

OTHER DOCUMENTS (Including Author, Title, Date, Portion, Pages, Etc.)


EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.